

3M to Present Paper on Embedded Capacitance and Board Level Reliability at IPC Second International Conference on Embedded Passives

IPC Second International Conference on Embedded Passives

The impact of 3M Embedded Capacitor Materials on board level reliability is the subject of a paper that will be presented by the 3M Electronic Solutions Division at IPC's Second International Conference on Embedded Passives 2004 in Santa Jose, Calif. The technical conference and exhibit will be held June 16-17 at the Crowne Plaza San Jose hotel.

The presentation "Impact of Embedded Capacitor Materials on Based Level Reliability" will take place June 16, from 1 p.m. to 4 p.m. Joel S. Peiffer, applications engineering specialist, 3M Corporate Research Materials Laboratory, will present information on a 3M laminate material that allows designers and manufacturers of high-speed digital printed circuit boards to achieve higher speeds while simplifying design tradeoffs. When used as a power-ground core in a multilayer printed circuit board, 3M embedded capacitor material effectively becomes a decoupling capacitor inside the board. The material allows designers to eliminate large numbers of decoupling capacitors, increases useable board area; enables faster signaling; lowers radiated emissions (EMI); and saves engineering time associated with power distribution design and board layout. Printed circuit board fabricators can use the material in military, automated test equipment, computer and telecommunications applications.

For additional information about this product from 3M, visit: <http://www.3m.com/ipc2004>.

About 3M Electronic Solutions Division

The 3M Electronic Solutions Division, headquartered in Austin, Texas, as a part of 3M Company, has numerous technologies and provides a wide range of products for the electronics market. It provides products and solutions to meet the electronic industry's challenges of protecting sensitive components and precisely delivering them to the assembly point, as well as flexible and multilayer microinterconnect packaging solutions; embedded capacitance laminate materials, copper and fiber interconnect systems; cables and cable assemblies; static control products, and test and burn-in sockets. The business is part of 3M Company, an \$18 billion diversified technology company with leading positions in consumer and office; display and graphics; electronics and telecommunications; health care; industrial; safety, security and protection services; transportation, and other businesses. More information on 3M flexible and multilayer solutions is available on the Internet at <http://www.3m.com/microinterconnect>.

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